



Welcome to [E-XFL.COM](https://www.e-xfl.com)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

| | |
|----------------------------|---|
| Product Status | Obsolete |
| Core Processor | ARM7® |
| Core Size | 16/32-Bit |
| Speed | 55MHz |
| Connectivity | I ² C, SPI, SSC, UART/USART, USB |
| Peripherals | Brown-out Detect/Reset, DMA, POR, PWM, WDT |
| Number of I/O | 32 |
| Program Memory Size | 128KB (128K x 8) |
| Program Memory Type | FLASH |
| EEPROM Size | - |
| RAM Size | 32K x 8 |
| Voltage - Supply (Vcc/Vdd) | 1.65V ~ 1.95V |
| Data Converters | A/D 8x10b |
| Oscillator Type | Internal |
| Operating Temperature | -40°C ~ 85°C |
| Mounting Type | Surface Mount |
| Package / Case | 64-VFQFN Exposed Pad |
| Supplier Device Package | 64-QFN (9x9) |
| Purchase URL | https://www.e-xfl.com/product-detail/microchip-technology/at91sam7s128c-mu-999 |

2. Block Diagram

Figure 2-1. SAM7S512/256/128/64/321/161 Block Diagram

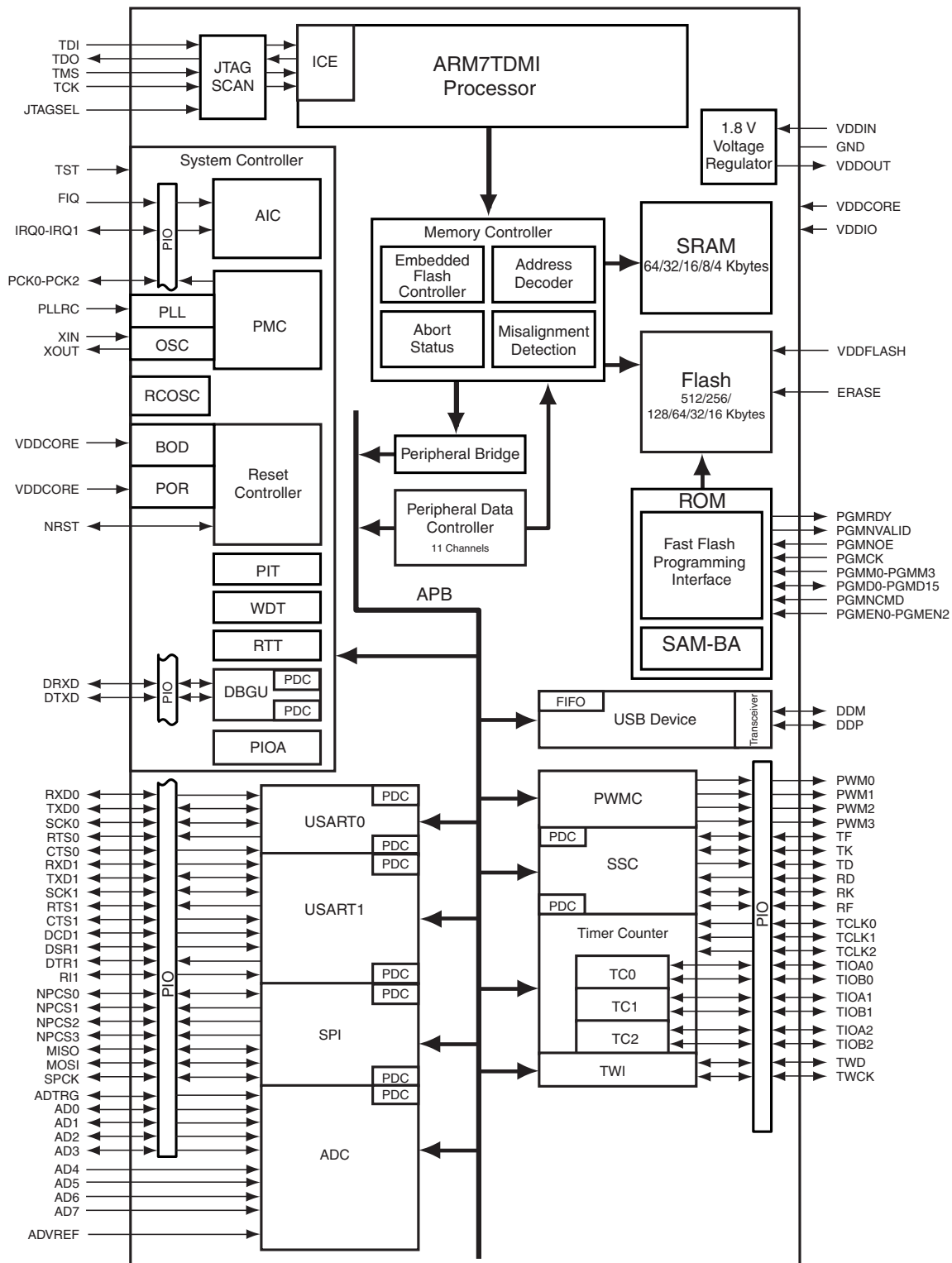
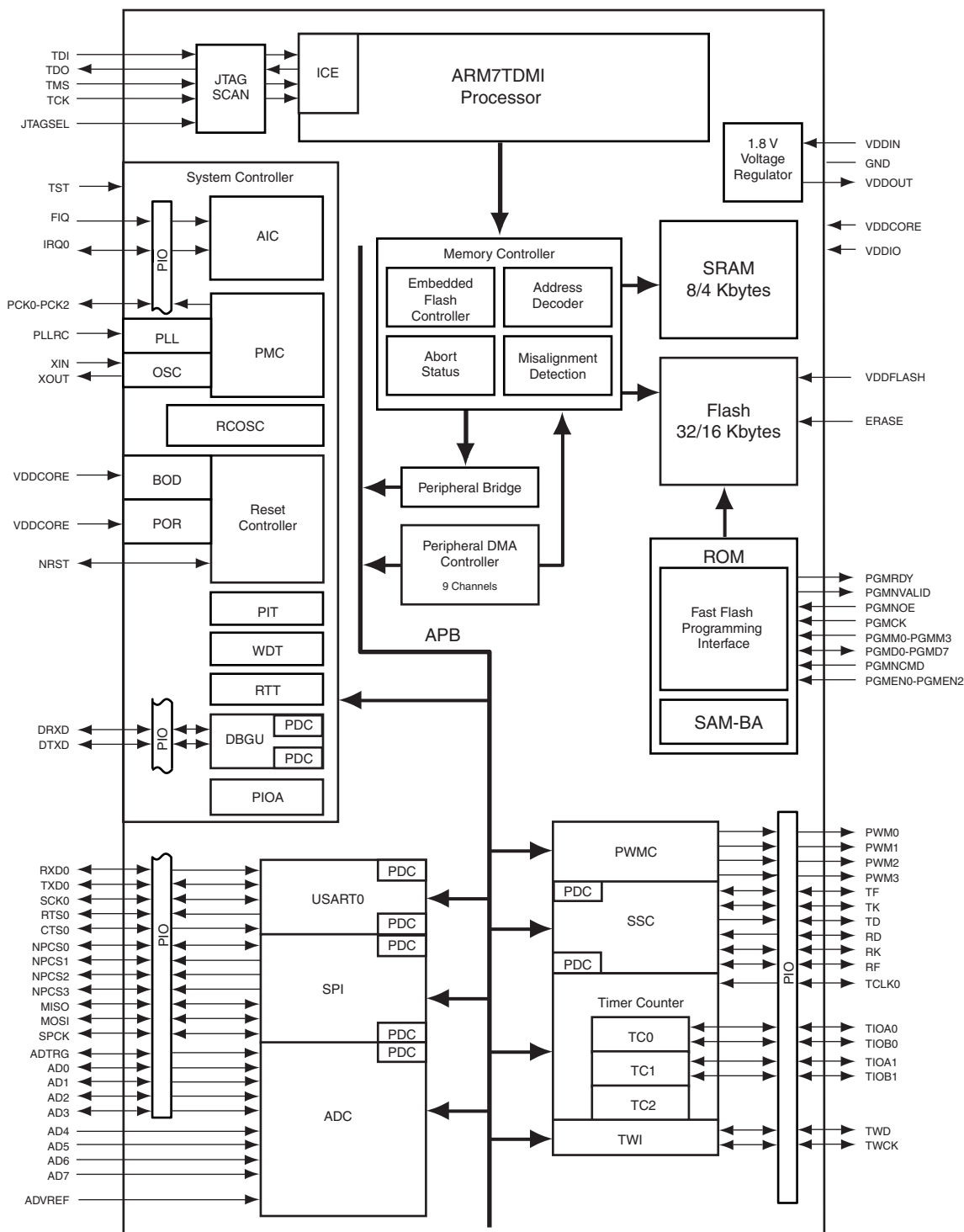


Figure 2-2. SAM7S32/16 Block Diagram



3. Signal Description

Table 3-1. Signal Description List

| VDDIN | Voltage and ADC Regulator Power Supply Input | Power | | 3.0 to 3.6V |
|-------------|--|--------|------|---|
| VDDOUT | Voltage Regulator Output | Power | | 1.85V nominal |
| VDDFLASH | Flash Power Supply | Power | | 3.0V to 3.6V |
| VDDIO | I/O Lines Power Supply | Power | | 3.0V to 3.6V or 1.65V to 1.95V |
| VDDCORE | Core Power Supply | Power | | 1.65V to 1.95V |
| VDDPLL | PLL | Power | | 1.65V to 1.95V |
| GND | Ground | Ground | | |
| XIN | Main Oscillator Input | Input | | |
| XOUT | Main Oscillator Output | Output | | |
| PLLRC | PLL Filter | Input | | |
| PCK0 - PCK2 | Programmable Clock Output | Output | | |
| TCK | Test Clock | Input | | No pull-up resistor |
| TDI | Test Data In | Input | | No pull-up resistor |
| TDO | Test Data Out | Output | | |
| TMS | Test Mode Select | Input | | No pull-up resistor |
| JTAGSEL | JTAG Selection | Input | | Pull-down resistor ⁽¹⁾ |
| ERASE | Flash and NVM Configuration Bits Erase Command | Input | High | Pull-down resistor ⁽¹⁾ |
| NRST | Microcontroller Reset | I/O | Low | Open-drain with pull-Up resistor |
| TST | Test Mode Select | Input | High | Pull-down resistor ⁽¹⁾ |
| DRXD | Debug Receive Data | Input | | |
| DTXD | Debug Transmit Data | Output | | |
| IRQ0 - IRQ1 | External Interrupt Inputs | Input | | IRQ1 not present on SAM7S32/16 |
| FIQ | Fast Interrupt Input | Input | | |
| PA0 - PA31 | Parallel IO Controller A | I/O | | Pulled-up input at reset PA0 - PA20 only on SAM7S32/16 |

4.2 64-lead LQFP and 64-pad QFN Pinout

Table 4-1. SAM7S512/256/128/64/321/161 Pinout⁽¹⁾

| | | | | | | | |
|----|----------------|----|---------------|----|-------------|----|-----------|
| 1 | ADVREF | 17 | GND | 33 | TDI | 49 | TDO |
| 2 | GND | 18 | VDDIO | 34 | PA6/PGMNOE | 50 | JTAGSEL |
| 3 | AD4 | 19 | PA16/PGMD4 | 35 | PA5/PGMRDY | 51 | TMS |
| 4 | AD5 | 20 | PA15/PGMD3 | 36 | PA4/PGMNCMD | 52 | PA31 |
| 5 | AD6 | 21 | PA14/PGMD2 | 37 | PA27/PGMD15 | 53 | TCK |
| 6 | AD7 | 22 | PA13/PGMD1 | 38 | PA28 | 54 | VDDCORE |
| 7 | VDDIN | 23 | PA24/PGMD12 | 39 | NRST | 55 | ERASE |
| 8 | VDDOUT | 24 | VDDCORE | 40 | TST | 56 | DDM |
| 9 | PA17/PGMD5/AD0 | 25 | PA25/PGMD13 | 41 | PA29 | 57 | DDP |
| 10 | PA18/PGMD6/AD1 | 26 | PA26/PGMD14 | 42 | PA30 | 58 | VDDIO |
| 11 | PA21/PGMD9 | 27 | PA12/PGMD0 | 43 | PA3 | 59 | VDDFLASH |
| 12 | VDDCORE | 28 | PA11/PGMM3 | 44 | PA2/PGMEN2 | 60 | GND |
| 13 | PA19/PGMD7/AD2 | 29 | PA10/PGMM2 | 45 | VDDIO | 61 | XOUT |
| 14 | PA22/PGMD10 | 30 | PA9/PGMM1 | 46 | GND | 62 | XIN/PGMCK |
| 15 | PA23/PGMD11 | 31 | PA8/PGMM0 | 47 | PA1/PGMEN1 | 63 | PLLRC |
| 16 | PA20/PGMD8/AD3 | 32 | PA7/PGMNVALID | 48 | PA0/PGMEN0 | 64 | VDDPLL |

Note: 1. The bottom pad of the QFN package must be connected to ground.

6. I/O Lines Considerations

6.1 JTAG Port Pins

TMS, TDI and TCK are schmitt trigger inputs. TMS and TCK are 5-V tolerant, TDI is not. TMS, TDI and TCK do not integrate a pull-up resistor.

TDO is an output, driven at up to VDDIO, and has no pull-up resistor.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. The JTAGSEL pin integrates a permanent pull-down resistor of about 15 k Ω to GND, so that it can be left unconnected for normal operations.

6.2 Test Pin

The TST pin is used for manufacturing test, fast programming mode or SAM-BA Boot Recovery of the SAM7S Series when asserted high. The TST pin integrates a permanent pull-down resistor of about 15 k Ω to GND, so that it can be left unconnected for normal operations.

To enter fast programming mode, the TST pin and the PA0 and PA1 pins should be tied high and PA2 tied to low.

To enter SAM-BA Boot Recovery, the TST pin and the PA0, PA1 and PA2 pins should be tied high for at least 10 seconds. Then a power cycle of the board is mandatory.

Driving the TST pin at a high level while PA0 or PA1 is driven at 0 leads to unpredictable results.

6.3 Reset Pin

The NRST pin is bidirectional with an open drain output buffer. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. There is no constraint on the length of the reset pulse, and the reset controller can guarantee a minimum pulse length. This allows connection of a simple push-button on the pin NRST as system user reset, and the use of the signal NRST to reset all the components of the system.

The NRST pin integrates a permanent pull-up resistor to VDDIO.

6.4 ERASE Pin

The ERASE pin is used to re-initialize the Flash content and some of its NVM bits. It integrates a permanent pull-down resistor of about 15 k Ω to GND, so that it can be left unconnected for normal operations.

6.5 PIO Controller A Lines

- All the I/O lines PA0 to PA31 on SAM7S512/256/128/64/321 (PA0 to PA20 on SAM7S32) are 5V-tolerant and all integrate a programmable pull-up resistor.
- All the I/O lines PA0 to PA31 on SAM7S161 (PA0 to PA20 on SAM7S16) are **not** 5V-tolerant and all integrate a programmable pull-up resistor.

Programming of this pull-up resistor is performed independently for each I/O line through the PIO controllers.

5V-tolerant means that the I/O lines can drive voltage level according to VDDIO, but can be driven with a voltage of up to 5.5V. However, driving an I/O line with a voltage over VDDIO while the programmable pull-up resistor is enabled will create a current path through the pull-up resistor from the I/O line to VDDIO. Care should be taken, in particular at reset, as all the I/O lines default to input with the pull-up resistor enabled at reset.

6.6 I/O Line Drive Levels

The PIO lines PA0 to PA3 are high-drive current capable. Each of these I/O lines can drive up to 16 mA permanently.

The remaining I/O lines can draw only 8 mA.

However, the total current drawn by all the I/O lines cannot exceed 150 mA (100 mA for SAM7S32/16).

7. Processor and Architecture

7.1 ARM7TDMI Processor

- RISC processor based on ARMv4T Von Neumann architecture
 - Runs at up to 55 MHz, providing 0.9 MIPS/MHz
- Two instruction sets
 - ARM® high-performance 32-bit instruction set
 - Thumb® high code density 16-bit instruction set
- Three-stage pipeline architecture
 - Instruction Fetch (F)
 - Instruction Decode (D)
 - Execute (E)

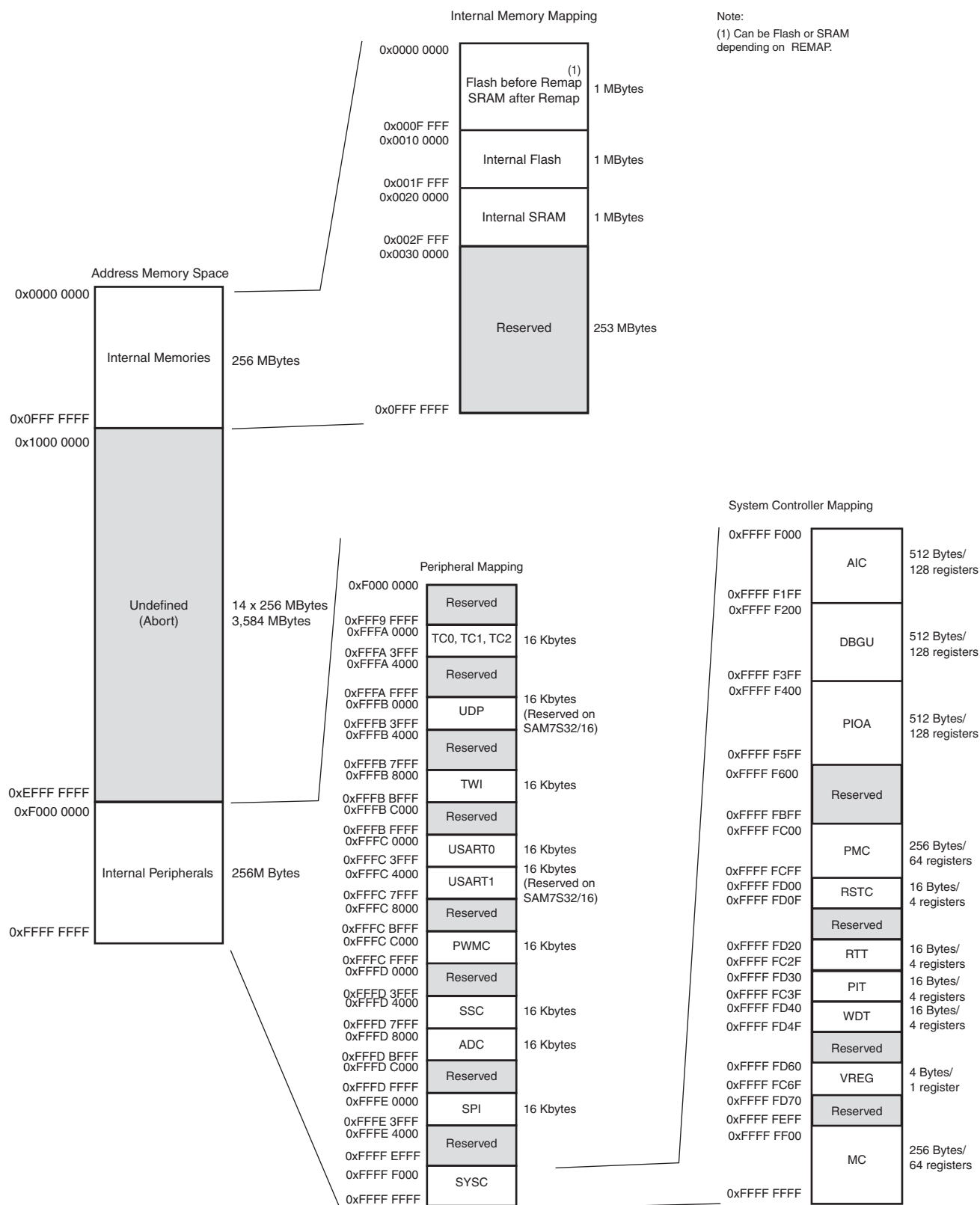
7.2 Debug and Test Features

- Integrated EmbeddedICE™ (embedded in-circuit emulator)
 - Two watchpoint units
 - Test access port accessible through a JTAG protocol
 - Debug communication channel
- Debug Unit
 - Two-pin UART
 - Debug communication channel interrupt handling
 - Chip ID Register
- IEEE1149.1 JTAG Boundary-scan on all digital pins

7.3 Memory Controller

- Bus Arbiter
 - Handles requests from the ARM7TDMI and the Peripheral DMA Controller
- Address decoder provides selection signals for
 - Three internal 1 Mbyte memory areas
 - One 256 Mbyte embedded peripheral area
- Abort Status Registers
 - Source, Type and all parameters of the access leading to an abort are saved
 - Facilitates debug by detection of bad pointers
- Misalignment Detector
 - Alignment checking of all data accesses
 - Abort generation in case of misalignment
- Remap Command
 - Remaps the SRAM in place of the embedded non-volatile memory
 - Allows handling of dynamic exception vectors
- Embedded Flash Controller
 - Embedded Flash interface, up to three programmable wait states
 - Prefetch buffer, buffering and anticipating the 16-bit requests, reducing the required wait states
 - Key-protected program, erase and lock/unlock sequencer
 - Single command for erasing, programming and locking operations
 - Interrupt generation in case of forbidden operation

Figure 8-1. SAM SAM7S512/256/128/64/321/32/161/16 Memory Mapping



8.8 Embedded Flash

8.8.1 Flash Overview

- The Flash of the SAM7S512 is organized in two banks (dual plane) of 1024 pages of 256 bytes. The 524,288 bytes are organized in 32-bit words.
- The Flash of the SAM7S256 is organized in 1024 pages (single plane) of 256 bytes. The 262,144 bytes are organized in 32-bit words.
- The Flash of the SAM7S128 is organized in 512 pages (single plane) of 256 bytes. The 131,072 bytes are organized in 32-bit words.
- The Flash of the SAM7S64 is organized in 512 pages (single plane) of 128 bytes. The 65,536 bytes are organized in 32-bit words.
- The Flash of the SAM7S321/32 is organized in 256 pages (single plane) of 128 bytes. The 32,768 bytes are organized in 32-bit words.
- The Flash of the SAM7S161/16 is organized in 256 pages (single plane) of 64 bytes. The 16,384 bytes are organized in 32-bit words.
- The Flash of the SAM7S512/256/128 contains a 256-byte write buffer, accessible through a 32-bit interface.
- The Flash of the SAM7S64/321/32/161/16 contains a 128-byte write buffer, accessible through a 32-bit interface.

The Flash benefits from the integration of a power reset cell and from the brownout detector. This prevents code corruption during power supply changes, even in the worst conditions.

When Flash is not used (read or write access), it is automatically placed into standby mode.

8.8.2 Embedded Flash Controller

The Embedded Flash Controller (EFC) manages accesses performed by the masters of the system. It enables reading the Flash and writing the write buffer. It also contains a User Interface, mapped within the Memory Controller on the APB. The User Interface allows:

- programming of the access parameters of the Flash (number of wait states, timings, etc.)
- starting commands such as full erase, page erase, page program, NVM bit set, NVM bit clear, etc.
- getting the end status of the last command
- getting error status
- programming interrupts on the end of the last commands or on errors

The Embedded Flash Controller also provides a dual 32-bit prefetch buffer that optimizes 16-bit access to the Flash. This is particularly efficient when the processor is running in Thumb mode.

Two EFCs are embedded in the SAM7S512 to control each bank of 256 Kbytes. Dual plane organization allows concurrent Read and Program. Read from one memory plane may be performed even while program or erase functions are being executed in the other memory plane.

One EFC is embedded in the SAM7S256/128/64/32/321/161/16 to control the single plane 256/128/64/32/16 Kbytes.

The 8 NVM bits are software programmable through the EFC User Interface. The command “Set Lock Bit” enables the protection. The command “Clear Lock Bit” unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

8.8.3.6 SAM7S161/16

The Embedded Flash Controller manages 8 lock bits to protect 8 regions of the flash against inadvertent flash erasing or programming commands. The SAM7S161/16 contains 8 lock regions and each lock region contains 32 pages of 64 bytes. Each lock region has a size of 2 Kbytes.

If a locked-region’s erase or program command occurs, the command is aborted and the LOCKE bit in the MC_FSR register rises and the interrupt line rises if the LOCKE bit has been written at 1 in the MC_FMR register.

The 8 NVM bits are software programmable through the EFC User Interface. The command “Set Lock Bit” enables the protection. The command “Clear Lock Bit” unlocks the lock region.

Asserting the ERASE pin clears the lock bits, thus unlocking the entire Flash.

Table 8-1 summarizes the configuration of the eight devices.

Table 8-1. Flash Configuration Summary

| SAM7S512 | 32 | 64 | 256 bytes |
|-------------|----|----|-----------|
| SAM7S256 | 16 | 64 | 256 bytes |
| SAM7S128 | 8 | 64 | 256 bytes |
| SAM7S64 | 16 | 32 | 128 bytes |
| SAM7S321/32 | 8 | 32 | 128 bytes |
| SAM7S161/16 | 8 | 32 | 64 bytes |

8.8.4 Security Bit Feature

The SAM7S Series features a security bit, based on a specific NVM Bit. When the security is enabled, any access to the Flash, either through the ICE interface or through the Fast Flash Programming Interface, is forbidden. This ensures the confidentiality of the code programmed in the Flash.

This security bit can only be enabled, through the Command “Set Security Bit” of the EFC User Interface. Disabling the security bit can only be achieved by asserting the ERASE pin at 1, and after a full flash erase is performed. When the security bit is deactivated, all accesses to the flash are permitted.

It is important to note that the assertion of the ERASE pin should always be longer than 50 ms.

As the ERASE pin integrates a permanent pull-down, it can be left unconnected during normal operation. However, it is safer to connect it directly to GND for the final application.

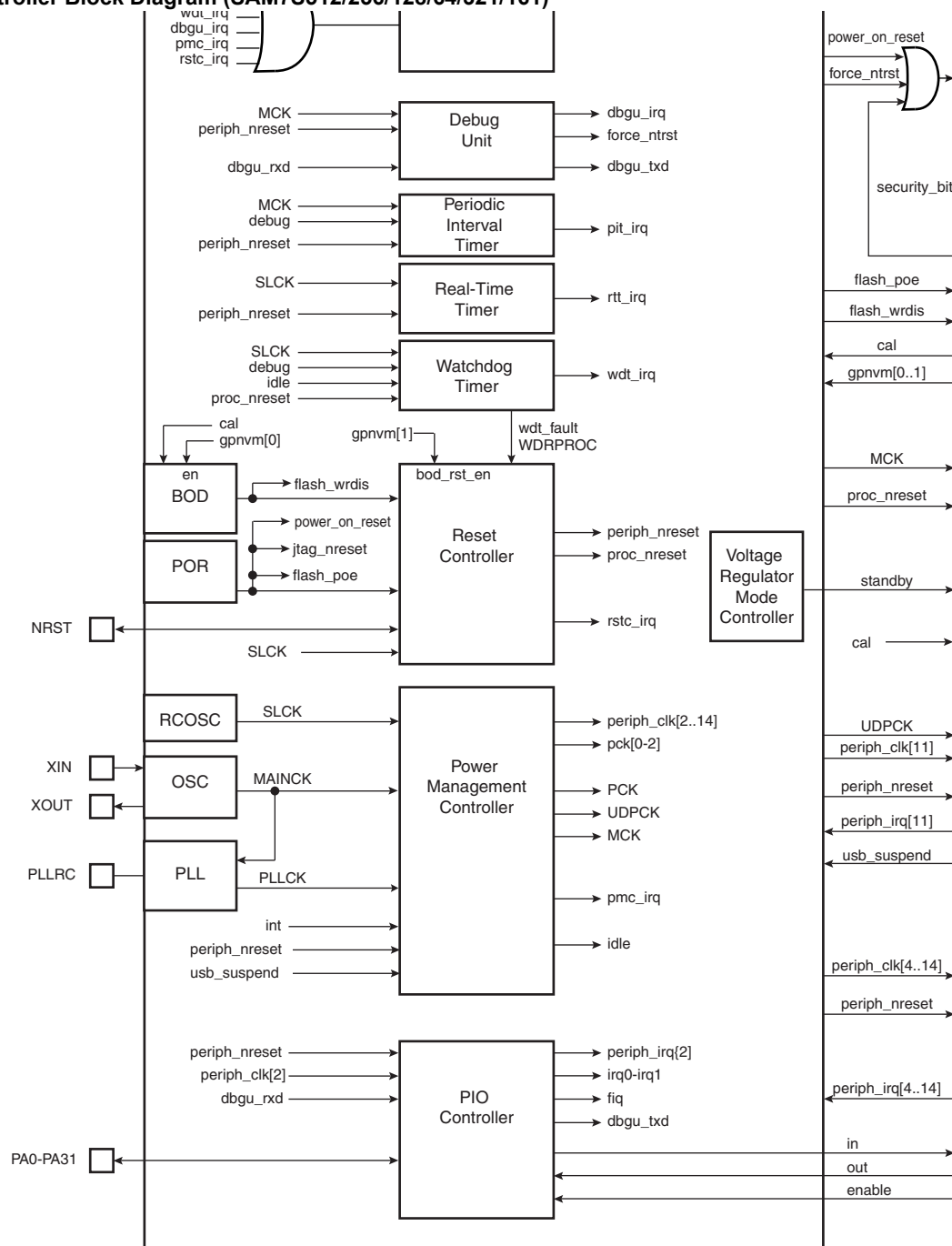
8.8.5 Non-volatile Brownout Detector Control

Two general purpose NVM (GPNVM) bits are used for controlling the brownout detector (BOD), so that even after a power loss, the brownout detector operations remain in their state.

These two GPNVM bits can be cleared or set respectively through the commands “Clear General-purpose NVM Bit” and “Set General-purpose NVM Bit” of the EFC User Interface.

- GPNVM Bit 0 is used as a brownout detector enable bit. Setting the GPNVM Bit 0 enables the BOD, clearing it disables the BOD. Asserting ERASE clears the GPNVM Bit 0 and thus disables the brownout detector by default.
- The GPNVM Bit 1 is used as a brownout reset enable signal for the reset controller. Setting the GPNVM Bit 1 enables the brownout reset when a brownout is detected, Clearing the GPNVM Bit 1 disables the brownout reset. Asserting ERASE disables the brownout reset by default.

Figure 9-1. System Controller Block Diagram (SAM7S512/256/128/64/321/161)



9.1 Reset Controller

The Reset Controller is based on a power-on reset cell and one brownout detector. It gives the status of the last reset, indicating whether it is a power-up reset, a software reset, a user reset, a watchdog reset or a brownout reset. In addition, it controls the internal resets and the NRST pin open-drain output. It allows to shape a signal on the NRST line, guaranteeing that the length of the pulse meets any requirement.

Note that if NRST is used as a reset output signal for external devices during power-off, the brownout detector must be activated.

9.1.1 Brownout Detector and Power-on Reset

The SAM7S Series embeds a brownout detection circuit and a power-on reset cell. Both are supplied with and monitor VDDCORE. Both signals are provided to the Flash to prevent any code corruption during power-up or power-down sequences or if brownouts occur on the VDDCORE power supply.

The power-on reset cell has a limited-accuracy threshold at around 1.5V. Its output remains low during power-up until VDDCORE goes over this voltage level. This signal goes to the reset controller and allows a full re-initialization of the device.

The brownout detector monitors the VDDCORE level during operation by comparing it to a fixed trigger level. It secures system operations in the most difficult environments and prevents code corruption in case of brownout on the VDDCORE.

Only VDDCORE is monitored.

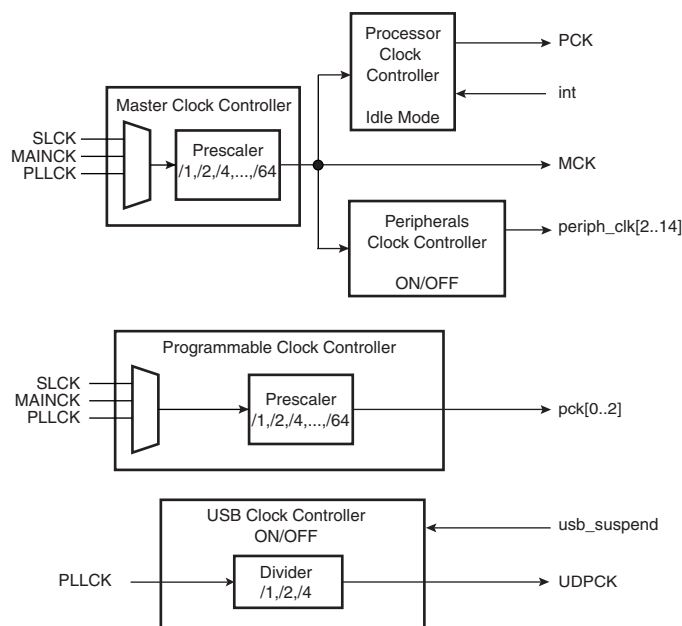
When the brownout detector is enabled and VDDCORE decreases to a value below the trigger level (V_{bot-} , defined as $V_{bot} - hyst/2$), the brownout output is immediately activated.

When VDDCORE increases above the trigger level (V_{bot+} , defined as $V_{bot} + hyst/2$), the reset is released. The brownout detector only detects a drop if the voltage on VDDCORE stays below the threshold voltage for longer than about 1 μ s.

The threshold voltage has a hysteresis of about 50 mV, to ensure spike free brownout detection. The typical value of the brownout detector threshold is 1.68V with an accuracy of $\pm 2\%$ and is factory calibrated.

The brownout detector is low-power, as it consumes less than 20 μ A static current. However, it can be deactivated to save its static current. In this case, it consumes less than 1 μ A. The deactivation is configured through the GPNVM bit 0 of the Flash.

Figure 9-4. Power Management Controller Block Diagram



9.4 Advanced Interrupt Controller

- Controls the interrupt lines (nIRQ and nFIQ) of an ARM Processor
- Individually maskable and vectored interrupt sources
 - Source 0 is reserved for the Fast Interrupt Input (FIQ)
 - Source 1 is reserved for system peripherals RTT, PIT, EFC, PMC, DBGU, etc.)
 - Other sources control the peripheral interrupts or external interrupts
 - Programmable edge-triggered or level-sensitive internal sources
 - Programmable positive/negative edge-triggered or high/low level-sensitive external sources
- 8-level Priority Controller
 - Drives the normal interrupt of the processor
 - Handles priority of the interrupt sources
 - Higher priority interrupts can be served during service of lower priority interrupt
- Vectoring
 - Optimizes interrupt service routine branch and execution
 - One 32-bit vector register per interrupt source
 - Interrupt vector register reads the corresponding current interrupt vector
- Protect Mode
 - Easy debugging by preventing automatic operations
- Fast Forcing
 - Permits redirecting any interrupt source on the fast interrupt
- General Interrupt Mask
 - Provides processor synchronization on events without triggering an interrupt

9.5 Debug Unit

- Comprises:
 - One two-pin UART
 - One Interface for the Debug Communication Channel (DCC) support

10. Peripherals

10.1 User Interface

The User Peripherals are mapped in the 256 MBytes of address space between 0xF000 0000 and 0xFFFF EFFF. Each peripheral is allocated 16 Kbytes of address space.

A complete memory map is provided in [Figure 8-1 on page 20](#).

10.2 Peripheral Identifiers

The SAM7S Series embeds a wide range of peripherals. [Table 10-1](#) defines the Peripheral Identifiers of the SAM7S512/256/128/64/321/161. [Table 10-2](#) defines the Peripheral Identifiers of the SAM7S32/16. A peripheral identifier is required for the control of the peripheral interrupt with the Advanced Interrupt Controller and for the control of the peripheral clock with the Power Management Controller.

Table 10-1. Peripheral Identifiers (SAM7S512/256/128/64/321/161)

| 0 | AIC | Advanced Interrupt Controller | FIQ |
|---------|---------------------|-------------------------------|------|
| 1 | SYSC ⁽¹⁾ | System | |
| 2 | PIOA | Parallel I/O Controller A | |
| 3 | Reserved | | |
| 4 | ADC ⁽¹⁾ | Analog-to Digital Converter | |
| 5 | SPI | Serial Peripheral Interface | |
| 6 | US0 | USART 0 | |
| 7 | US1 | USART 1 | |
| 8 | SSC | Synchronous Serial Controller | |
| 9 | TWI | Two-wire Interface | |
| 10 | PWMC | PWM Controller | |
| 11 | UDP | USB Device Port | |
| 12 | TC0 | Timer/Counter 0 | |
| 13 | TC1 | Timer/Counter 1 | |
| 14 | TC2 | Timer/Counter 2 | |
| 15 - 29 | Reserved | | |
| 30 | AIC | Advanced Interrupt Controller | IRQ0 |
| 31 | AIC | Advanced Interrupt Controller | IRQ1 |

Note: 1. Setting SYSC and ADC bits in the clock set/clear registers of the PMC has no effect. The System Controller is continuously clocked. The ADC clock is automatically started for the first conversion. In Sleep Mode the ADC clock is automatically stopped after each conversion.

Note: 1. Setting SYSC and ADC bits in the clock set/clear registers of the PMC has no effect. The System Controller is continuously clocked. The ADC clock is automatically started for the first conversion. In Sleep Mode the ADC clock is automatically stopped after each conversion.

10.4 PIO Controller A Multiplexing

Table 10-3. Multiplexing on PIO Controller A (SAM7S512/256/128/64/321/161)

| PA0 | PWM0 | TIOA0 | High-Drive | | |
|------|-------|-------|------------|--|--|
| PA1 | PWM1 | TIOB0 | High-Drive | | |
| PA2 | PWM2 | SCK0 | High-Drive | | |
| PA3 | TWD | NPCS3 | High-Drive | | |
| PA4 | TWCK | TCLK0 | | | |
| PA5 | RXD0 | NPCS3 | | | |
| PA6 | TXD0 | PCK0 | | | |
| PA7 | RTS0 | PWM3 | | | |
| PA8 | CTS0 | ADTRG | | | |
| PA9 | DRXD | NPCS1 | | | |
| PA10 | DTXD | NPCS2 | | | |
| PA11 | NPCS0 | PWM0 | | | |
| PA12 | MISO | PWM1 | | | |
| PA13 | MOSI | PWM2 | | | |
| PA14 | SPCK | PWM3 | | | |
| PA15 | TF | TIOA1 | | | |
| PA16 | TK | TIOB1 | | | |
| PA17 | TD | PCK1 | AD0 | | |
| PA18 | RD | PCK2 | AD1 | | |
| PA19 | RK | FIQ | AD2 | | |
| PA20 | RF | IRQ0 | AD3 | | |
| PA21 | RXD1 | PCK1 | | | |
| PA22 | TXD1 | NPCS3 | | | |
| PA23 | SCK1 | PWM0 | | | |
| PA24 | RTS1 | PWM1 | | | |
| PA25 | CTS1 | PWM2 | | | |
| PA26 | DCD1 | TIOA2 | | | |
| PA27 | DTR1 | TIOB2 | | | |
| PA28 | DSR1 | TCLK1 | | | |
| PA29 | RI1 | TCLK2 | | | |
| PA30 | IRQ1 | NPCS2 | | | |
| PA31 | NPCS1 | PCK2 | | | |

10.5 Serial Peripheral Interface

- Supports communication with external serial devices
 - Four chip selects with external decoder allow communication with up to 15 peripherals
 - Serial memories, such as DataFlash® and 3-wire EEPROMs
 - Serial peripherals, such as ADCs, DACs, LCD Controllers, CAN Controllers and Sensors
 - External co-processors
- Master or slave serial peripheral bus interface
 - 8- to 16-bit programmable data length per chip select
 - Programmable phase and polarity per chip select
 - Programmable transfer delays between consecutive transfers and between clock and data per chip select
 - Programmable delay between consecutive transfers
 - Selectable mode fault detection
 - Maximum frequency at up to Master Clock

10.6 Two-wire Interface

- Master Mode only (SAM7S512/256/128/64/321/32)
- Master, Multi-Master and Slave Mode support (SAM7S161/16)
- General Call supported in Slave Mode (SAM7S161/16)
- Compatibility with I²C compatible devices (refer to the TWI sections of the datasheet)
- One, two or three bytes internal address registers for easy Serial Memory access
- 7-bit or 10-bit slave addressing
- Sequential read/write operations

10.7 USART

- Programmable Baud Rate Generator
- 5- to 9-bit full-duplex synchronous or asynchronous serial communications
 - 1, 1.5 or 2 stop bits in Asynchronous Mode
 - 1 or 2 stop bits in Synchronous Mode
 - Parity generation and error detection
 - Framing error detection, overrun error detection
 - MSB or LSB first
 - Optional break generation and detection
 - By 8 or by 16 over-sampling receiver frequency
 - Hardware handshaking RTS - CTS
 - Modem Signals Management DTR-DSR-DCD-RI on USART1 (not present on SAM7S32/16)
 - Receiver time-out and transmitter timeguard
 - Multi-drop Mode with address generation and detection
- RS485 with driver control signal
- ISO7816, T = 0 or T = 1 Protocols for interfacing with smart cards
 - NACK handling, error counter with repetition and iteration limit
- IrDA modulation and demodulation
 - Communication at up to 115.2 Kbps
- Test Modes
 - Remote Loopback, Local Loopback, Automatic Echo

11. Package Drawings

The SAM7S series devices are available in LQFP and QFN package types.

11.1 LQFP Packages

Figure 11-1. 48-and 64-lead LQFP Package Drawing

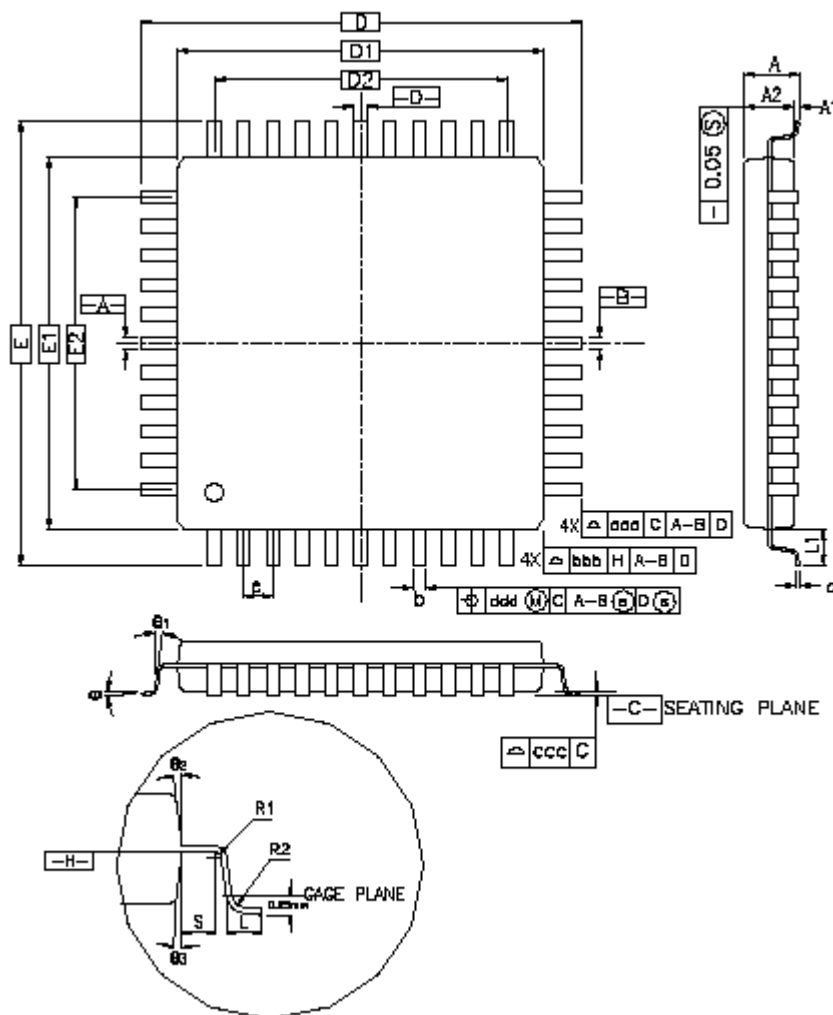


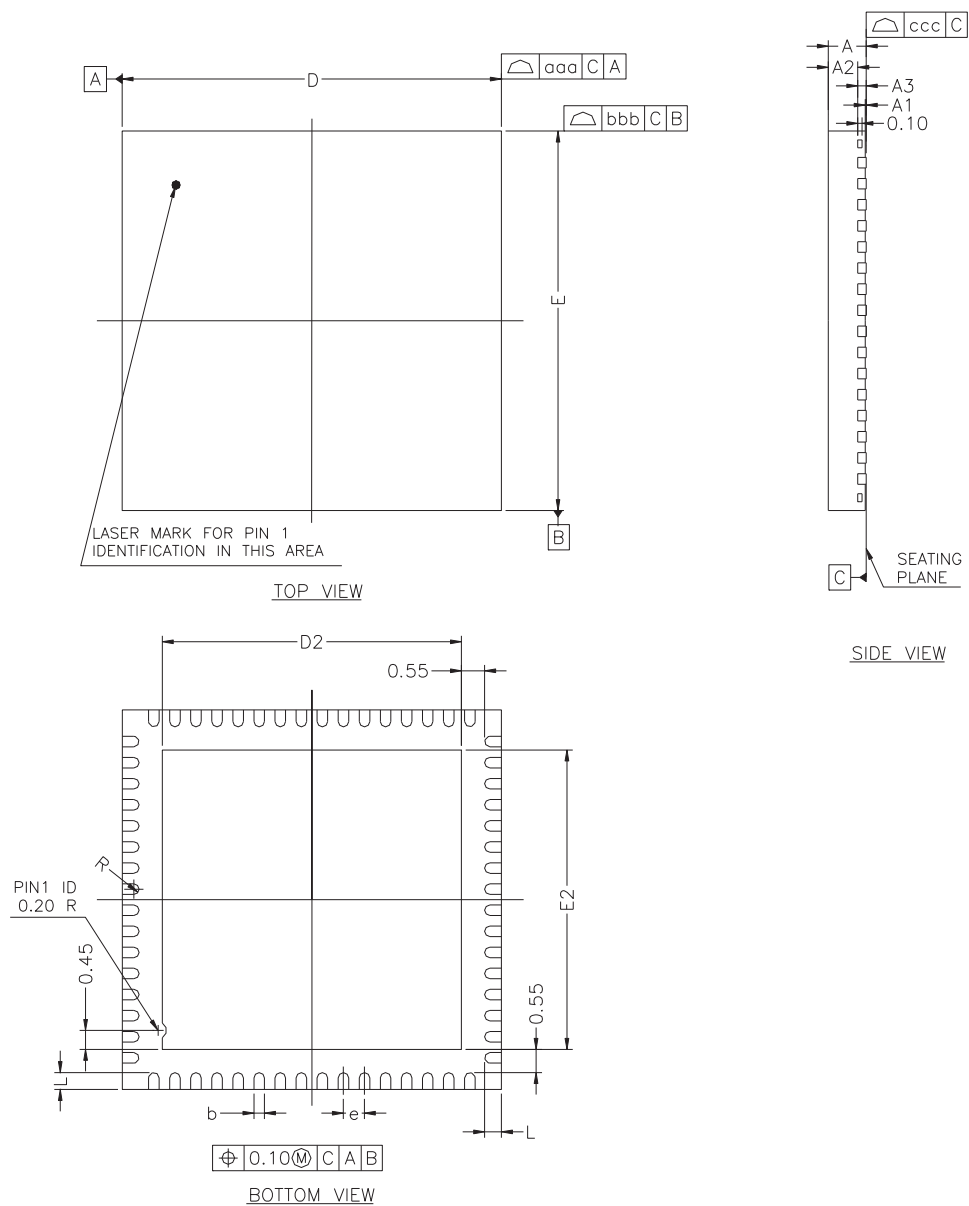
Table 11-1. 48-lead LQFP Package Dimensions (in mm)

| Symbol | | | | | | |
|---------------------------------|-----------|------|------|------------|-------|-------|
| | | | | | | |
| A | – | – | 1.60 | – | – | 0.063 |
| A1 | 0.05 | – | 0.15 | 0.002 | – | 0.006 |
| A2 | 1.35 | 1.40 | 1.45 | 0.053 | 0.055 | 0.057 |
| D | 9.00 BSC | | | 0.354 BSC | | |
| D1 | 7.00 BSC | | | 0.276 BSC | | |
| E | 9.00 BSC | | | 0.354 BSC | | |
| E1 | 7.00 BSC | | | 0.276 BSC | | |
| R2 | 0.08 | – | 0.20 | 0.003 | – | 0.008 |
| R1 | 0.08 | – | – | 0.003 | – | – |
| q | 0° | 3.5° | 7° | 0° | 3.5° | 7° |
| θ ₁ | 0° | – | – | 0° | – | – |
| θ ₂ | 11° | 12° | 13° | 11° | 12° | 13° |
| θ ₃ | 11° | 12° | 13° | 11° | 12° | 13° |
| c | 0.09 | – | 0.20 | 0.004 | – | 0.008 |
| L | 0.45 | 0.60 | 0.75 | 0.018 | 0.024 | 0.030 |
| L1 | 1.00 REF | | | 0.039 REF | | |
| S | 0.20 | – | – | 0.008 | – | – |
| b | 0.17 | 0.20 | 0.27 | 0.007 | 0.008 | 0.011 |
| e | 0.50 BSC. | | | 0.020 BSC. | | |
| D2 | 5.50 | | | 0.217 | | |
| E2 | 5.50 | | | 0.217 | | |
| Tolerances of Form and Position | | | | | | |
| aaa | 0.20 | | | 0.008 | | |
| bbb | 0.20 | | | 0.008 | | |
| ccc | 0.08 | | | 0.003 | | |
| ddd | 0.08 | | | 0.003 | | |

Table 11-2. 64-lead LQFP Package Dimensions (in mm)

| Symbol | | | | | | |
|---------------------------------|-----------|------|------|------------|-------|-------|
| | | | | | | |
| A | – | – | 1.60 | – | – | 0.063 |
| A1 | 0.05 | – | 0.15 | 0.002 | – | 0.006 |
| A2 | 1.35 | 1.40 | 1.45 | 0.053 | 0.055 | 0.057 |
| D | 12.00 BSC | | | 0.472 BSC | | |
| D1 | 10.00 BSC | | | 0.383 BSC | | |
| E | 12.00 BSC | | | 0.472 BSC | | |
| E1 | 10.00 BSC | | | 0.383 BSC | | |
| R2 | 0.08 | – | 0.20 | 0.003 | – | 0.008 |
| R1 | 0.08 | – | – | 0.003 | – | – |
| q | 0° | 3.5° | 7° | 0° | 3.5° | 7° |
| θ ₁ | 0° | – | – | 0° | – | – |
| θ ₂ | 11° | 12° | 13° | 11° | 12° | 13° |
| θ ₃ | 11° | 12° | 13° | 11° | 12° | 13° |
| c | 0.09 | – | 0.20 | 0.004 | – | 0.008 |
| L | 0.45 | 0.60 | 0.75 | 0.018 | 0.024 | 0.030 |
| L1 | 1.00 REF | | | 0.039 REF | | |
| S | 0.20 | – | – | 0.008 | – | – |
| b | 0.17 | 0.20 | 0.27 | 0.007 | 0.008 | 0.011 |
| e | 0.50 BSC. | | | 0.020 BSC. | | |
| D2 | 7.50 | | | 0.285 | | |
| E2 | 7.50 | | | 0.285 | | |
| Tolerances of Form and Position | | | | | | |
| aaa | 0.20 | | | 0.008 | | |
| bbb | 0.20 | | | 0.008 | | |
| ccc | 0.08 | | | 0.003 | | |
| ddd | 0.08 | | | 0.003 | | |

Figure 11-3. 64-pad QFN Package Drawing





Enabling Unlimited Possibilities®

Atmel Corporation

1600 Technology Drive
San Jose, CA 95110
USA

Tel: (+1) (408) 441-0311

Fax: (+1) (408) 487-2600

www.atmel.com

Atmel Asia Limited

Unit 01-5 & 16, 19F
BEA Tower, Millennium City 5
418 Kwun Tong Roa

Kwun Tong, Kowloon

HONG KONG

Tel: (+852) 2245-6100

Fax: (+852) 2722-1369

Atmel Munich GmbH

Business Campus
Parking 4
D-85748 Garching b. Munich
GERMANY

Tel: (+49) 89-31970-0

Fax: (+49) 89-3194621

Atmel Japan G.K.

16F Shin-Osaki Kangyo Bldg
1-6-4 Osaki, Shinagawa-ku
Tokyo 141-0032

JAPAN

Tel: (+81) (3) 6417-0300

Fax: (+81) (3) 6417-0370

© 2012 Atmel Corporation. All rights reserved. / Rev.: 6175KS-ATARM-25-Oct-12

Atmel®, Atmel logo and combinations thereof, Enabling Unlimited Possibilities®, SAM-BA® and others, are registered trademarks or trademarks of Atmel Corporation or its subsidiaries. Windows® and others are registered trademarks or trademarks of Microsoft Corporation in the US and/or in other countries. ARM®, the ARM Powered® logo, ARM7TDMI®, Thumb®, and others are registered trademarks or trademarks of ARM Limited. Other terms and product names may be the trademarks of others.

Disclaimer: The information in this document is provided in connection with Atmel products. No license, express or implied, by estoppel or otherwise, to any intellectual property right is granted by this document or in connection with the sale of Atmel products. EXCEPT AS SET FORTH IN THE ATMEL TERMS AND CONDITIONS OF SALES LOCATED ON THE ATMEL WEBSITE, ATMEL ASSUMES NO LIABILITY WHATSOEVER AND DISCLAIMS ANY EXPRESS, IMPLIED OR STATUTORY WARRANTY RELATING TO ITS PRODUCTS INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTY OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT. IN NO EVENT SHALL ATMEL BE LIABLE FOR ANY DIRECT, INDIRECT, CONSEQUENTIAL, PUNITIVE, SPECIAL OR INCIDENTAL DAMAGES (INCLUDING, WITHOUT LIMITATION, DAMAGES FOR LOSS AND PROFITS, BUSINESS INTERRUPTION, OR LOSS OF INFORMATION) ARISING OUT OF THE USE OR INABILITY TO USE THIS DOCUMENT, EVEN IF ATMEL HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. Atmel makes no representations or warranties with respect to the accuracy or completeness of the contents of this document and reserves the right to make changes to specifications and products descriptions at any time without notice. Atmel does not make any commitment to update the information contained herein. Unless specifically provided otherwise, Atmel products are not suitable for, and shall not be used in, automotive applications. Atmel products are not intended, authorized, or warranted for use as components in applications intended to support or sustain life.